

- Use **CDCVF2509A** as a Replacement for this Device
- Designed to Meet PC SDRAM Registered DIMM Specification
- Spread Spectrum Clock Compatible
- Operating Frequency 25 MHz to 125 MHz
- Phase Error Time Minus Jitter at 66 MHz to 100 MHz Is ± 150 ps
- Jitter (peak – peak) at 66 MHz to 100 MHz Is ± 80 ps
- Jitter (cycle – cycle) at 66 MHz to 100 MHz Is ± 100 ps
- Available in Plastic 24-Pin TSSOP
- Phase-Lock Loop Clock Distribution for Synchronous DRAM Applications
- Distributes One Clock Input to One Bank of Five and One Bank of Four Outputs
- Separate Output Enable for Each Output Bank
- External Feedback (FBIN) Terminal Is Used to Synchronize the Outputs to the Clock Input
- On-Chip Series Damping Resistors
- No External RC Network Required
- Operates at 3.3 V

PW PACKAGE
(TOP VIEW)



description

The CDC2509B is a high-performance, low-skew, low-jitter, phase-lock loop (PLL) clock drivers. They use a PLL to precisely align, in both frequency and phase, the feedback (FBOUT) output to the clock (CLK) input signal. They are specifically designed for use with synchronous DRAMs. The CDC2509B operates at 3.3-V V_{CC} . They also provide integrated series-damping resistors that make it ideal for driving point-to-point loads.

One bank of five outputs and one bank of four outputs provide nine low-skew, low-jitter copies of CLK. Output signal duty cycles are adjusted to 50%, independent of the duty cycle at CLK. Each bank of outputs is enabled or disabled separately via the control (1G and 2G) inputs. When the G inputs are high, the outputs switch in phase and frequency with CLK; when the G inputs are low, the outputs are disabled to the logic-low state.

Unlike many products containing PLLs, the CDC2509B does not require external RC networks. The loop filter for the PLL is included on-chip, minimizing component count, board space, and cost.

Because it is based on PLL circuitry, the CDC2509B requires a stabilization time to achieve phase lock of the feedback signal to the reference signal. This stabilization time is required, following power up and application of a fixed-frequency, fixed-phase signal at CLK, and following any changes to the PLL reference or feedback signals. The PLL can be bypassed for test purposes by strapping AV_{CC} to ground.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

TEXAS
INSTRUMENTS

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CDC2509B
3.3-V PHASE-LOCK LOOP CLOCK DRIVER

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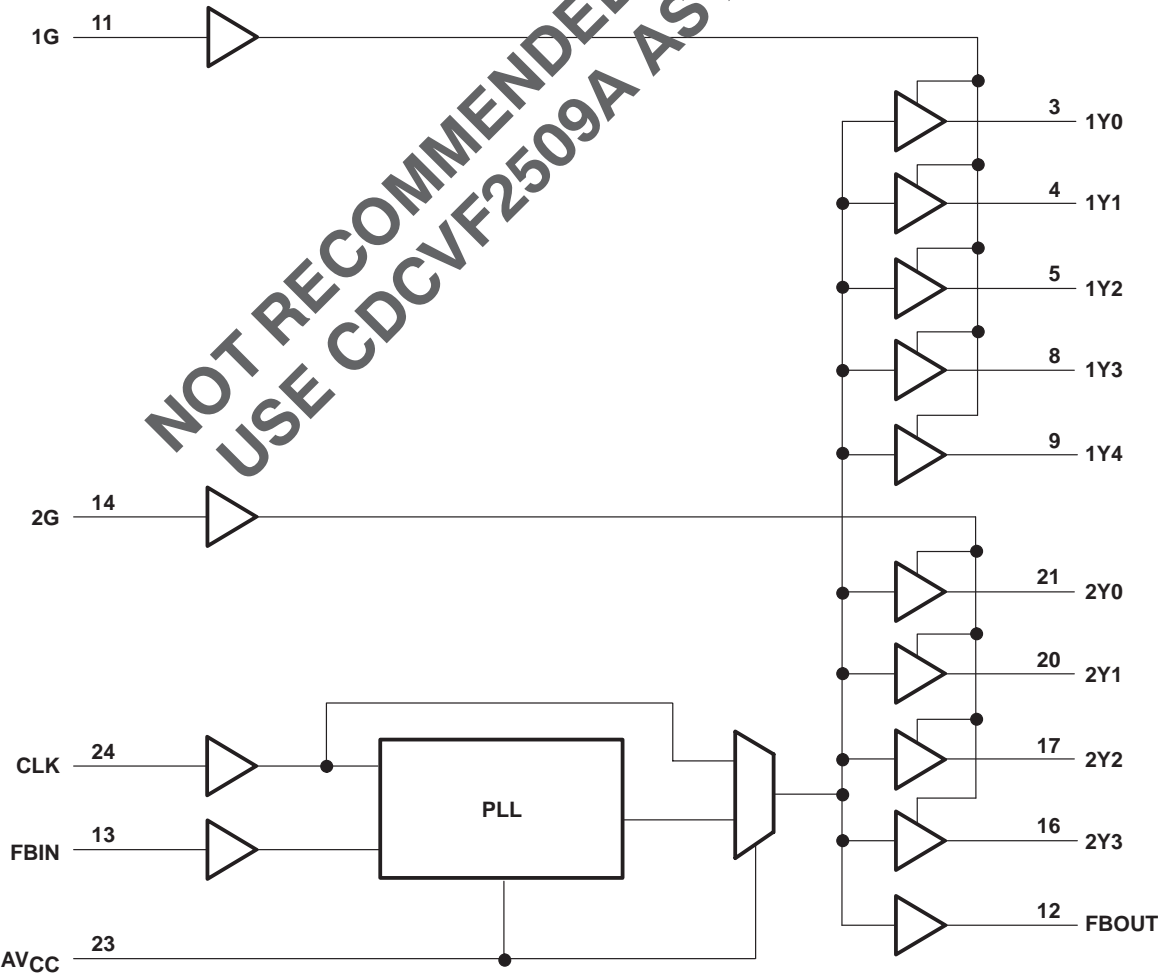
description (continued)

The CDC2509B is characterized for operation from 0°C to 70°C.

For application information refer to application reports *High Speed Distribution Design Techniques for CDC509/516/2509/2510/2516* (literature number SLMA003) and *Using CDC2509A/2510A PLL with Spread Spectrum Clocking (SSC)* (literature number SCAA039).

FUNCTION TABLE					
INPUTS			OUTPUTS		
1G	2G	CLK	1Y (0:4)	2Y (0:3)	FBOUT
X	X	L	L	L	L
L	L	H	L	L	H
L	H	H	L	H	H
H	L	H	H	L	H
H	H	H	H	H	H

functional block diagram



AVAILABLE OPTIONS

CDC2509B

3.3-V PHASE-LOCK LOOP CLOCK DRIVER

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T _A	PACKAGE
	SMALL OUTLINE (PW)
0°C to 70°C	CDC2509BPWR

Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
CLK	24	I	Clock input. CLK provides the clock signal to be distributed by the CDC2509B and the CDC2510B clock drivers. CLK is used to provide the reference signal to the integrated PLL that generates the clock output signals. CLK must have a fixed frequency and fixed phase for the PLL to obtain phase lock. Once the circuit is powered up and a valid CLK signal is applied, a stabilization time is required for the PLL to phase lock the feedback signal to its reference signal.
FBIN	13	I	Feedback input. FBIN provides the feedback signal to the internal PLL. FBIN must be hard-wired to FBOUT to complete the PLL. The integrated PLL synchronizes CLK and FBIN so that there is nominally zero phase error between CLK and FBIN.
1G	11	I	Output bank enable. 1G is the output enable for outputs 1Y(0:4). When 1G is low, outputs 1Y(0:4) are disabled to a logic-low state. When 1G is high, all outputs 1Y(0:4) are enabled and switch at the same frequency as CLK.
2G	14	I	Output bank enable. 2G is the output enable for outputs 2Y(0:3). When 2G is low, outputs 2Y(0:3) are disabled to a logic-low state. When 2G is high, all outputs 2Y(0:3) are enabled and switch at the same frequency as CLK.
FBOUT	12	O	Feedback output. FBOUT is dedicated for external feedback. It switches at the same frequency as CLK. When externally wired to FBIN, FBOUT completes the feedback loop of the PLL. FBOUT has an integrated 25-Ω series-damping resistor.
1Y (0:4)	3, 4, 5, 8, 9	O	Clock outputs. These outputs provide low-skew copies of CLK. Output bank 1Y(0:4) is enabled via the 1G input. These outputs can be disabled to a logic-low state by deasserting the 1G control input. Each output has an integrated 25-Ω series-damping resistor.
2Y (0:3)	16, 17, 20, 21	O	Clock outputs. These outputs provide low-skew copies of CLK. Output bank 2Y(0:3) is enabled via the 2G input. These outputs can be disabled to a logic-low state by deasserting the 2G control input. Each output has an integrated 25-Ω series-damping resistor.
AV _{CC}	23	Power	Analog power supply. AV _{CC} provides the power reference for the analog circuitry. In addition, AV _{CC} can be used to bypass the PLL for test purposes. When AV _{CC} is strapped to ground, PLL is bypassed and CLK is buffered directly to the device outputs.
AGND	1	Ground	Analog ground. AGND provides the ground reference for the analog circuitry.
V _{CC}	2, 10, 15, 22	Power	Power supply
GND	6, 7, 18, 19	Ground	Ground

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Table with 2 columns: Parameter and Rating. Parameters include Supply voltage range, Input voltage range, Voltage range applied to any output, Input clamp current, Output clamp current, Continuous output current, Continuous current through each VCC or GND, Maximum power dissipation, and Storage temperature range.

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

- NOTES: 1. AVCC must not exceed VCC.
2. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
3. This value is limited to 4.6 V maximum.
4. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 5)

Table with 4 columns: Parameter, MIN, MAX, UNIT. Parameters include Supply voltage, High-level input voltage, Low-level input voltage, Input voltage, High-level output current, Low-level output current, and Operating free-air temperature.

NOTE 5: Unused inputs must be held high or low to prevent them from floating.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{CC} , AV _{CC}	MIN	TYP†	MAX	UNIT
V _{IK}	I _I = -18 mA		3 V			-1.2	V
V _{OH}	I _{OH} = -100 μA		MIN to MAX	V _{CC} -0.2			V
	I _{OH} = -12 mA		3 V	2.1			
	I _{OH} = -6 mA		3 V	2.4			
V _{OL}	I _{OL} = 100 μA		MIN to MAX			0.2	V
	I _{OL} = 12 mA		3 V			0.8	
	I _{OL} = 6 mA		3 V			0.55	
I _I	V _I = V _{CC} or GND		3.6 V			±5	μA
I _{CC} ‡	V _I = V _{CC} or GND, I _O = 0, Outputs: low or high		3.6 V			10	μA
ΔI _{CC}	One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND		3.3 V to 3.6 V			500	μA
C _i	V _I = V _{CC} or GND		3.3 V			4	pF
C _o	V _O = V _{CC} or GND		3.3 V			6	pF

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ For I_{CC} of AV_{CC}, and I_{CC} vs Frequency (see Figures 7 and 8).

timing requirements over recommended ranges of supply voltage and operating free-air temperature

	MIN	MAX	UNIT
f _{clk} Clock frequency	25	125	MHz
Input clock duty cycle	40%	60%	
Stabilization time§	1		ms

§ Time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. For phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at CLK. Until phase lock is obtained, the specifications for propagation delay, skew, and jitter parameters given in the switching characteristics table are not applicable. This parameter does not apply for input modulation under SSC application.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 30 pF (see Note 6 and Figures 1 and 2)¶

PARAMETER	FROM (INPUT)/CONDITION	TO (OUTPUT)	V _{CC} , AV _{CC} = 3.3 V ± 0.165 V			V _{CC} , AV _{CC} = 3.3 V ± 0.3 V			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
t _{phase error} : - jitter (see Notes 7 and 8, Figures 3, 4, and 5)	CLKIN↑ = 66 MHz to 100 MHz	FBIN↑	-150		150	-200		200	ps
t _{sk(o)} #	Any Y or FBOUT	Any Y or FBOUT						200	ps
Jitter(pk-pk) (see Figure 6)	CLKIN = 66 MHz to 100 MHz	Any Y or FBOUT				-80		80	ps
Jitter(cycle-cycle) (see Figure 6)		Any Y or FBOUT						100	
Duty cycle	F(CLKIN > 60 MHz)	Any Y or FBOUT				45%		55%	
t _r		Any Y or FBOUT		1.3	1.9	0.8		2.1	ns
t _f		Any Y or FBOUT		1.7	2.5	1.2		2.7	ns

¶ These parameters are not production tested.

The t_{sk(o)} specification is only valid for equal loading of all outputs.

NOTES: 6. The specifications for parameters in this table are applicable only after any appropriate stabilization time has elapsed.

7. This is considered as static phase error.

8. Phase error does not include jitter. The total phase error is -230 ps to 230 ps for the 5% V_{CC} range.

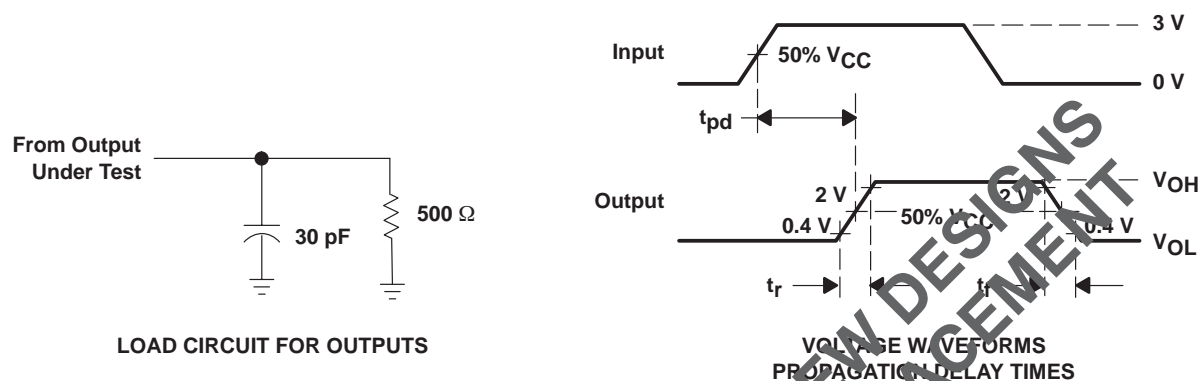


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3.3-V PHASE-LOCK LOOP CLOCK DRIVER

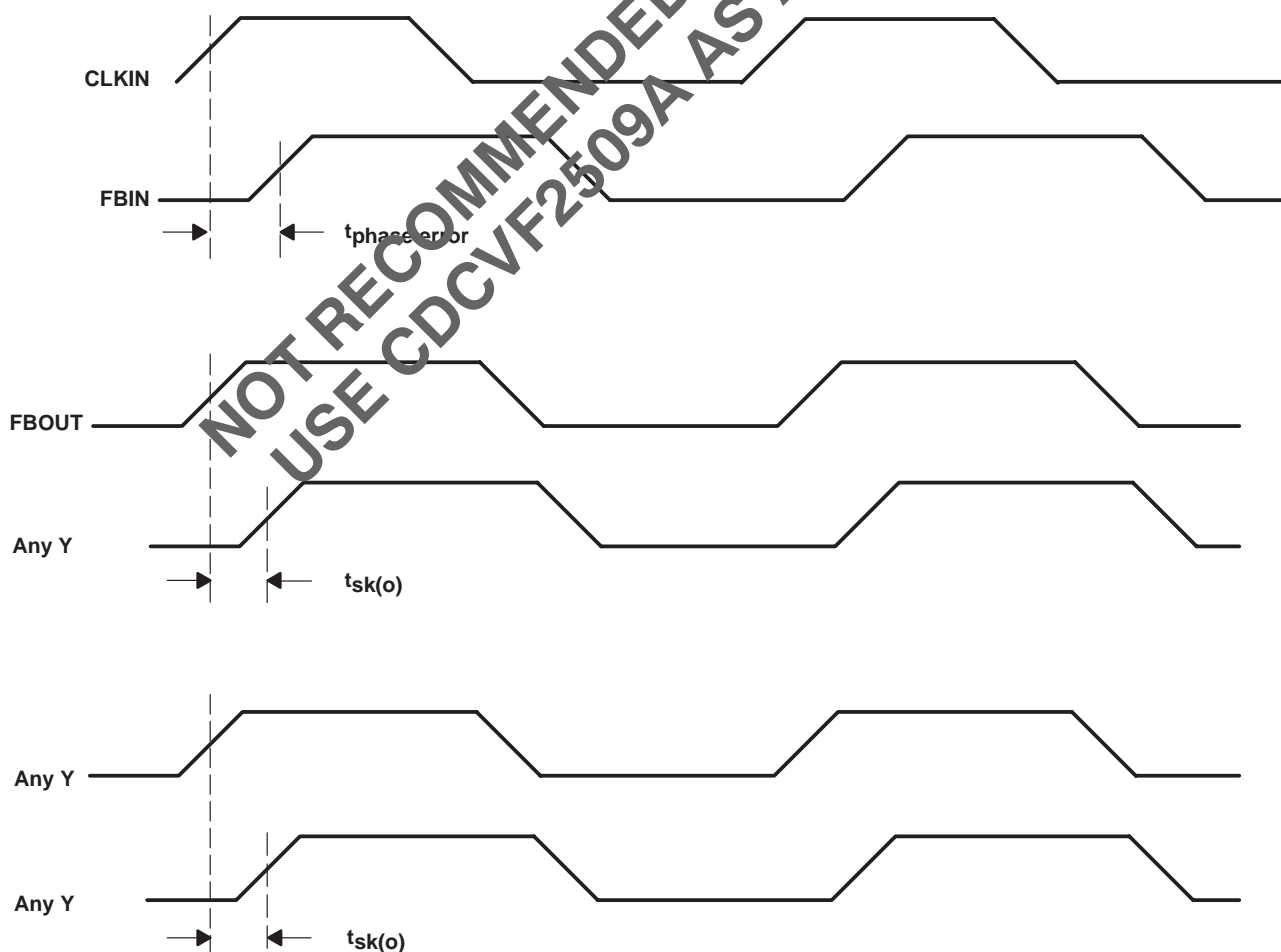
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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: $PRN \leq 100$ MHz, $Z_O = 50 \Omega$, $t_r \leq 1.2$ ns, $t_f \leq 1.2$ ns.
C. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



TYPICAL CHARACTERISTICS

PHASE ADJUSTMENT SLOPE AND PHASE ERROR vs LUMPED FEEDBACK CAPACITANCE AT FBIN

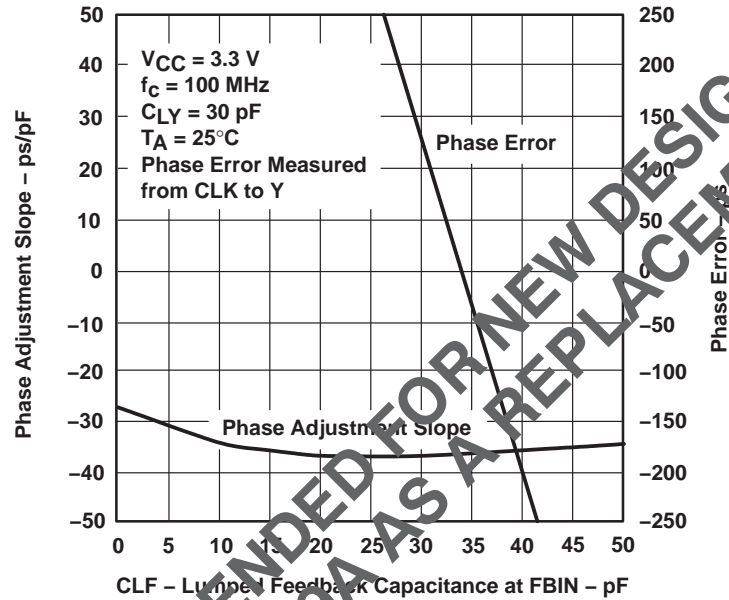


Figure 3

PHASE ERROR vs CLOCK FREQUENCY

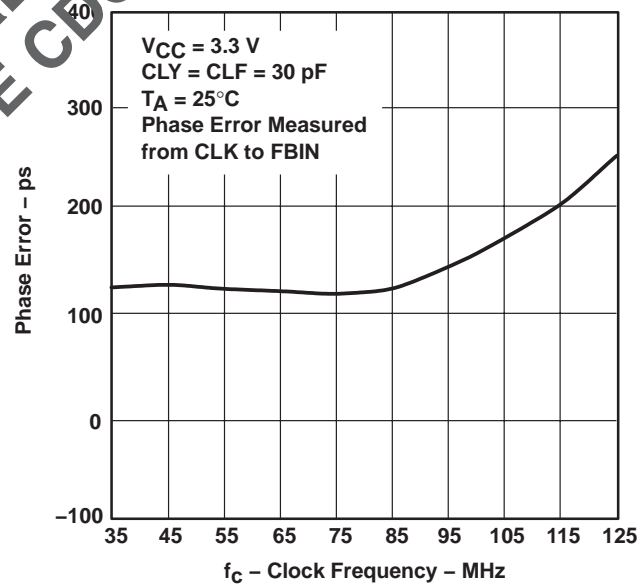


Figure 4

- NOTES: A. CL_Y = Lumped capacitive load at Y
B. CL_F = Lumped feedback capacitance at FBIN

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TYPICAL CHARACTERISTICS

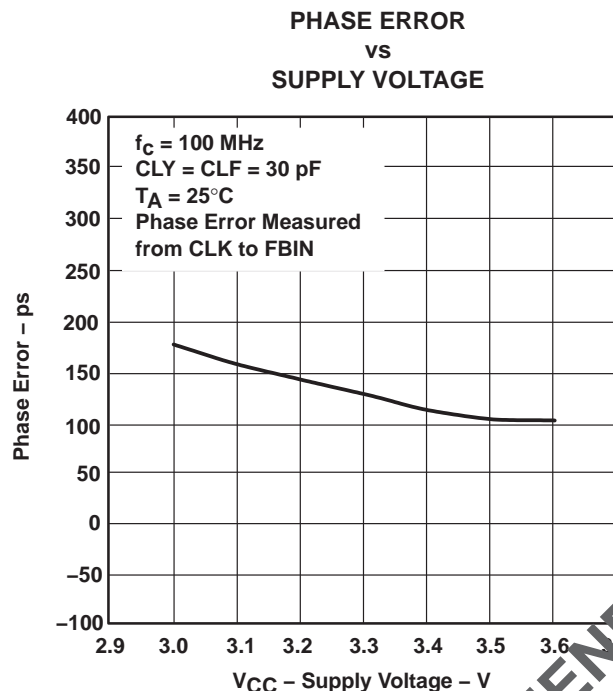


Figure 5

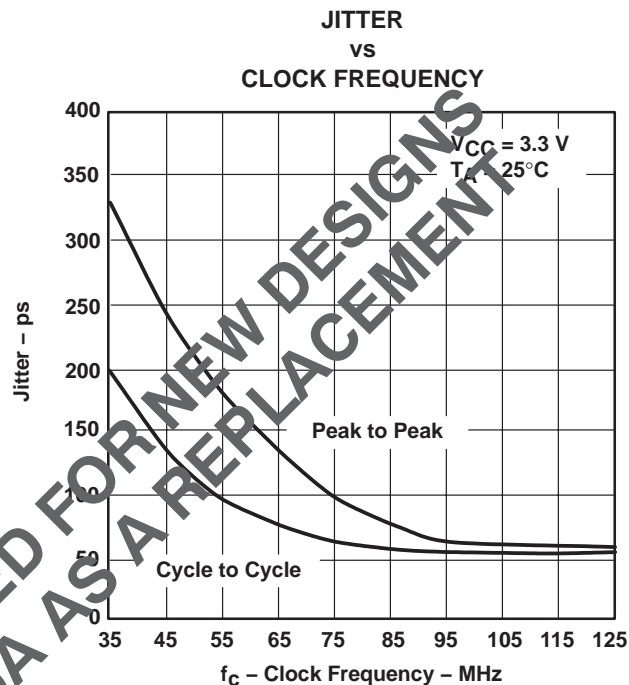


Figure 6

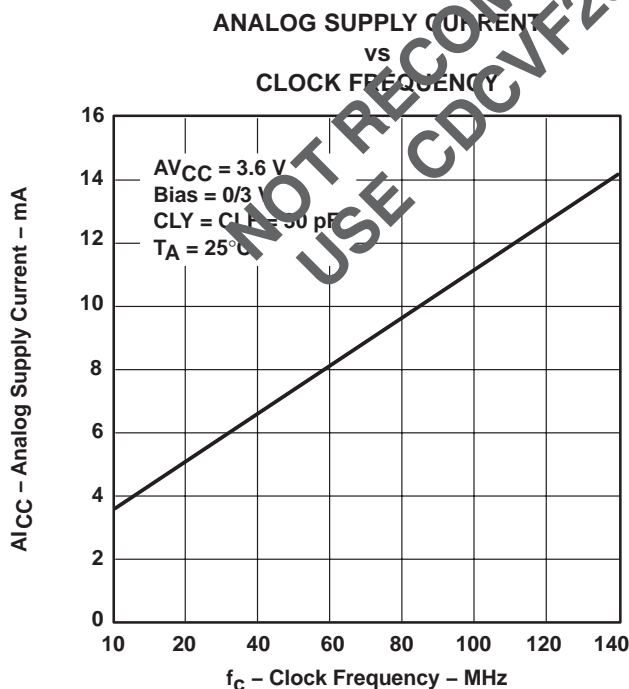


Figure 7

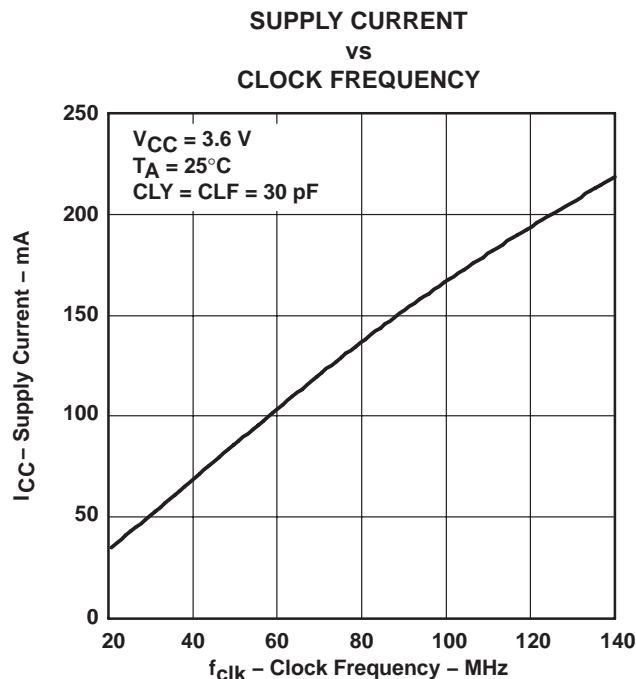


Figure 8

NOTES: A. CLY = Lumped capacitive load at Y
 B. CLF = Lumped feedback capacitance at FBIN

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CDC2509BPWR	NRND	Production	TSSOP (PW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	CK2509B
CDC2509BPWR.B	NRND	Production	TSSOP (PW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	CK2509B

- (1) **Status:** For more details on status, see our [product life cycle](#).
- (2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
- (3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.
- (4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

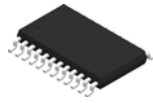
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDC2509BPWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDC2509BPWR	TSSOP	PW	24	2000	353.0	353.0	32.0



4220208/A 02/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220208/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220208/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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